

TK31N60X-VB Datasheet N-Channel 600V (D-S) Super Junction Power MOSFET

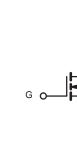
PRODUCT SUMM	ARY	
V _{DS} (V) at T _J max.	600	0
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.085

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
 - Fluorescent ballast lighting



N-Channel MOSFET





Top View

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30	7 v	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	32		
		T _C = 100 °C		20	Α	
Pulsed Drain Current ^a			I _{DM}	96		
Linear Derating Factor				1.67	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	920	mJ	
Maximum Power Dissipation			P_{D}	510	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		d\//d±	50	1//20	
Reverse Diode dV/dt ^d			dV/dt	15	- V/ns	
Soldering Recommendations (Peak Temperature) ^c	for	10 s		260	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_{J}=25$ °C, L = 30mH, $R_{g}=25$ Ω , $I_{AS}=16A$.

- c. 1.6 mm from case. d. $I_{SD} \le I_D$, dl/dt = 100 A/ μ s, starting T_J = 25 °C.



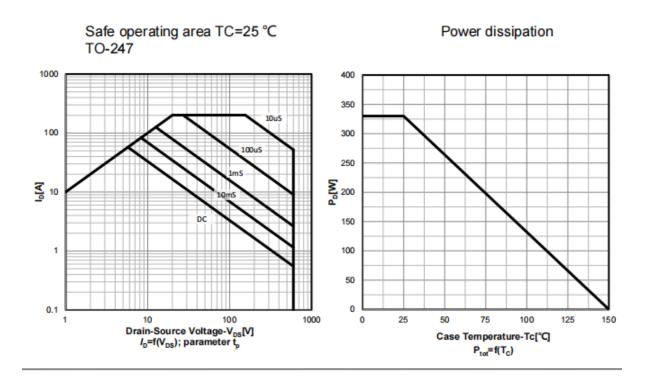
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.38	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					•
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} =	= 0 V, I _D = 1 mA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	-	4.5	V
		,	V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I_{GSS}		V _{GS} = ± 30 V	_	_	± 1	μΑ
			= 600V, V _{GS} = 0 V	_	_	1	<u> </u>
Zero Gate Voltage Drain Current	I _{DSS}		V, V _{GS} = 0 V, T _J = 125 °C	-	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =10.5A	-	0.085	-	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 10.5 A	-	5.6	-	S
Dynamic		•					
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	3400	-	pF
Output Capacitance	Coss			-	330	-	
Reverse Transfer Capacitance	C _{rss}			-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	- V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	63	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-	
Total Gate Charge	Qg			-	410	-	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	-	39	-	nC
Gate-Drain Charge	Q _{gd}	1		-	4 7	-	
Turn-On Delay Time	t _{d(on)}			-	18	25	
Rise Time	t _r	V _{DD} = 520 V, I _D = 20A,		-	24	55	ns
Turn-Off Delay Time	t _{d(off)}			-	8 0	-	
Fall Time	t _f	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	1 2	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	8.0	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	32	
Pulsed Diode Forward Current	I _{SM}			-	-	96	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	-	1.5	V
Reverse Recovery Time	t _{rr}			-	520	-	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 8 A, dl/dt = 100 A/ μ s, V _R = 400 V		_	5.8	-	μC
Reverse Recovery Current	I _{RRM}				4 5		A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





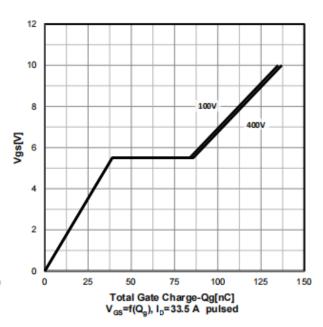
Typ. output characteristics T_i =25 $^{\circ}$ C Transfer characteristics 300 300 25°C . I_D, Drain Current [A] Drain Current [A] 200 150°C -0 5 10 0 15 20 0 2 10 12 V_{GS}, Gate-Source Voltage [V] V_{DS}, Drain to Source Voltage [V]



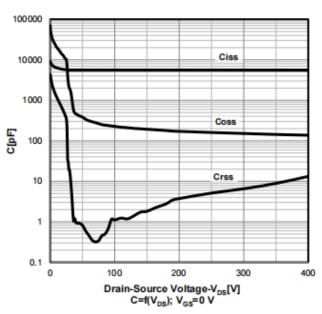
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter: V_{GS}

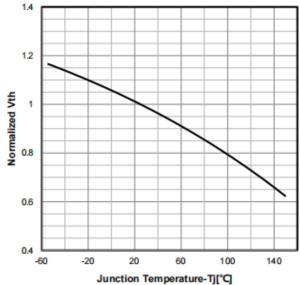
Typ. gate charge characteristics



Typ. capacitances



Normalized $V_{\text{GS(th)}}$ characteristics

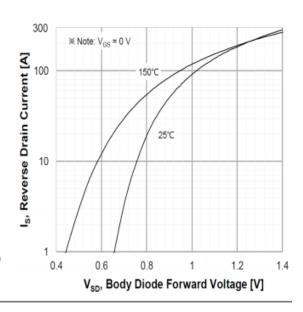




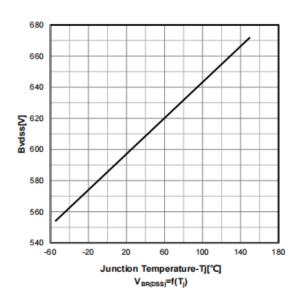
On-resistance vs temperature

120 100 80 40 40 20 40 Junction Temperature-Ti[°C] R_{DS}(on)=f(Tj); I_D=33.5 A; V_{OS}=10 V

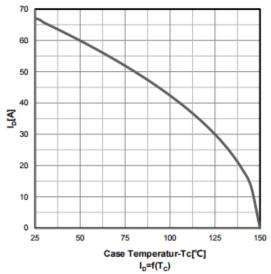
Forward characteristics of reverse diode



Drain-source breakdown voltage



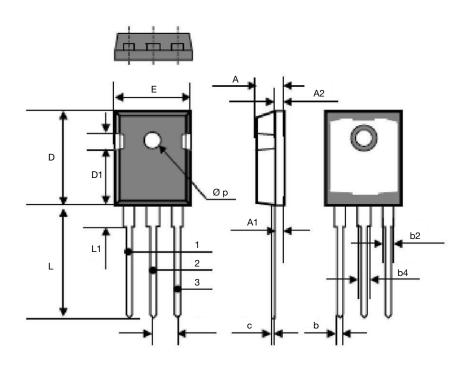
Drain current vs temperature



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DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61 BSC		0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46 BSC		0.215 BSC		
E	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	



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